

**Business Overview**

The Integrated Modules & Devices segment handles communications devices, power modules, and other equipment with our high reliability electronic components to meet the specific needs of various markets.

**Business Performance in the Year Ended March 2014**

Segment net sales decreased 11.4% year over year to ¥42,375 million due to year-over-year declines in sales of SAW/FBAR devices for mobile communications and power supply modules.

**Key Initiatives in the Year Ended March 2014**

During the term, the Group developed products centered on SAW technology, which is used as the fundamental mobile communications devices in smartphones. We also developed and submitted product proposals for products including miniaturized, low energy-consumption filter devices for long-term evolution, or LTE, transmission method that has been gaining usage in recent years, and front-end modules with matching circuits. In addition, a key focus remains on the development of products using FBAR technology to provide solutions for devices with higher functionality.

In mixed-function modules, EOMIN™, an embedded-parts multilayer wiring

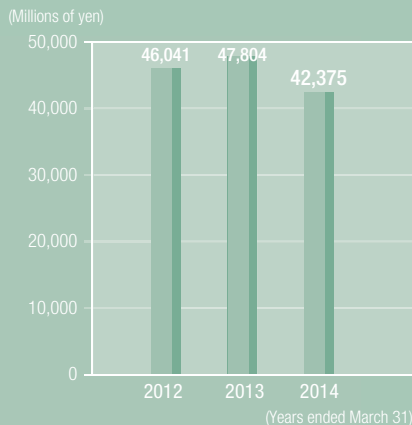
substrate, contributed substantially to making smaller and thinner camera modules for smartphones.

In wireless communication modules, we concentrated on developing and commercializing combination modules with universal compatibility with Bluetooth®, wireless LAN, and other communications standards.

**Initiatives Ahead**

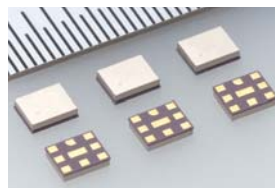
The Group is developing a high frequency module business centered on SAW/FBAR technology, aggressively introducing super high-end products using the Group's original embedded-parts multilayer wiring substrate EOMIN™ technology, and strengthening the power supply business with recovery systems and other products for the energy market. We will also construct production systems for mobile communications devices to keep pace with the rising number of built-in components accompanying broadening use of the next-generation LTE transmission method.

**Net sales**

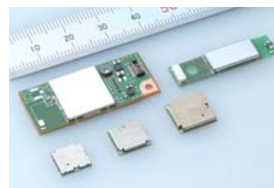


**Main Products**

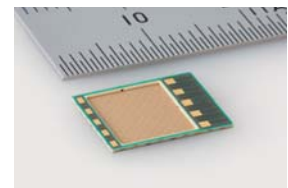
SAW/FBAR devices for mobile communications, power supply modules, high frequency modules and embedded-parts multilayer wiring substrate



SAW/FBAR devices for mobile communications



Wireless modules



Embedded-parts multilayer wiring substrate EOMIN™